

#### Absolute Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Collector-Base Voltage	V <sub>CBO</sub>	-100	V	
Collector-Emitter Voltage	V <sub>CEO</sub>	-80	V	
Emitter-Base Voltage	V <sub>EBO</sub>	-7	V	
Continuous Collector Current	Ic	-1	٨	
Peak Pulse Collector Current	I <sub>CM</sub>	-2	— A	
Continuous Base Current	IB	-100	mA	
Peak Pulse Base Current	I <sub>BM</sub>	-200		

### Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Power Dissipation	(Note 5)	PD	520	mW
Thermal Resistance, Junction to Ambient	(Note 5)	R <sub>0JA</sub>	240	°C /W
Thermal Resistance, Junction to Leads	(Note 6)	R <sub>θJL</sub>	20	°C/W
Operating and Storage Temperature Range		TJ, TSTG	-65 to +150	°C

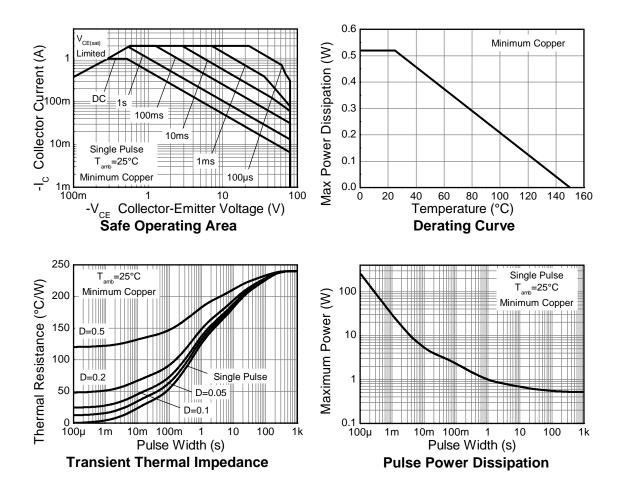
### ESD Ratings (Note 7)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	ЗA
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

5. For a device mounted on minimum recommended pad layout FR4 PCB single sided 1oz copper; device is measured under still air conditions while operating in a steady-state.
6. Thermal resistance from junction to solder-point (at the end of the collector lead).
7. Refer to JEDEC specification JESD22-A114 and JESD22-A115. Notes:



# Thermal Characteristics and Derating Information



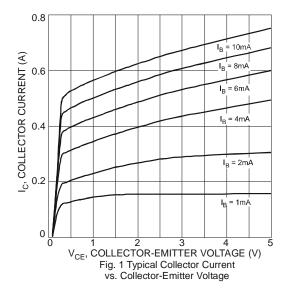


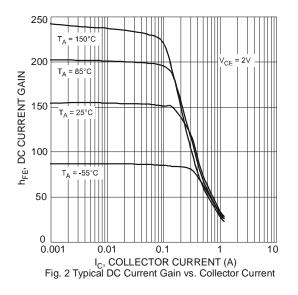
# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Мах	Unit	Test Condition
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	-100	-	-	V	I <sub>C</sub> = -100μA
Collector-Emitter Breakdown Voltage (Note 8)	BV <sub>CEO</sub>	-80	-	-	V	I <sub>C</sub> = -10mA
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	-7	-	-	V	I <sub>E</sub> = -100μA
Collector Cut-off Current	I <sub>CBO</sub>	-	-	-0.1 -20	μA	V <sub>CB</sub> = -30V V <sub>CB</sub> = -30V, T <sub>A</sub> = +150°C
Emitter Cut-off Current	I <sub>EBO</sub>	-	-	-20	nA	$V_{EB} = -4V$
Static Forward Current Transfer Ratio (Note 8)	h <sub>FE</sub>	25 100 25	- - -	- 250 -	-	$    I_{C} = -5mA, V_{CE} = -2V \\     I_{C} = -150mA, V_{CE} = -2V \\     I_{C} = -500mA, V_{CE} = -2V $
Collector-Emitter Saturation Voltage (Note 8)	V <sub>CE(sat)</sub>	-	-	-0.5	V	I <sub>C</sub> = -500mA, I <sub>B</sub> = -50mA
Base-Emitter Turn-On Voltage (Note 8)	V <sub>BE(on)</sub>	-	-	-1.0	V	$I_{C} = -500 \text{mA}, V_{CE} = -2 \text{V}$
Transition Frequency	f⊤	-	125	-	MHz	$I_{C} = -50 \text{mA}, V_{CE} = -10 \text{V}$ f = 100MHz
Output Capacitance	Cobo	-	-	25	pF	V <sub>CB</sub> = -10V, f = 1MHz

Note: 8. Measured under pulsed conditions. Pulse width  $\leq$  300µs. Duty cycle  $\leq$  2%.

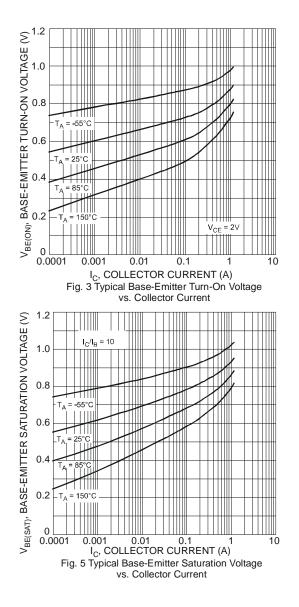
# **Typical Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

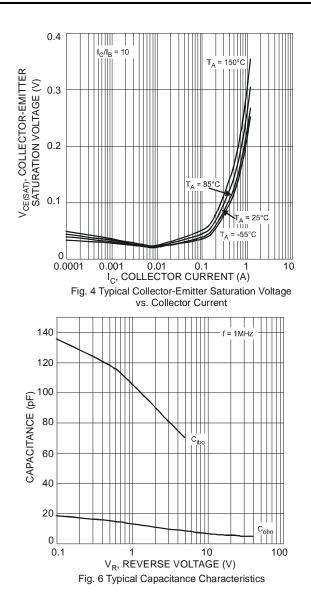






### Typical Electrical Characteristics (continued)

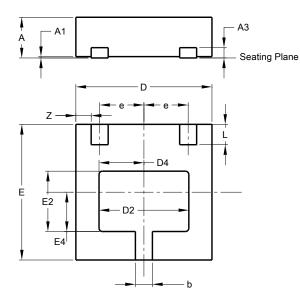






#### **Package Outline Dimensions**

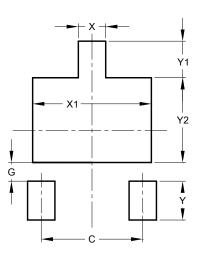
Please see AP02001 at http://www.diodes.com/\_files/datasheets/ap02001.pdf for the latest version.



U-DFN2020-3 (Type B)					
Dim	Min	Max	Тур		
Α	0.57	0.63	0.60		
A1	0.00	0.05	0.02		
A3			0.152		
b	0.20	0.30	0.25		
D	1.950	2.075	2.00		
D2	1.22	1.42	1.32		
D4	0.56	0.76	0.66		
E	1.950	2.075	2.00		
E2	0.79	0.99	0.89		
E4	0.48	0.68	0.58		
e			0.65		
L	0.25	0.35	0.30		
Z			0.225		
All Dimensions in mm					

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/\_files/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	1.300
G	0.240
Х	0.350
X1	1.520
X2	1.700
Y	0.500
Y1	0.470
Y2	1.090

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.



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